

**IN THE CLAIMS:**

The text of all pending claims, (including withdrawn claims) are set forth below. Cancelled and not entered claims are indicated with claim number and status only. The claims as listed below show added text with underlining and deleted text with ~~strikethrough~~. The status of each claim is indicated with one of (original), (currently amended), (cancelled), (withdrawn), (new), (previously presented), or (not entered). Please AMEND claims and ADD new claims, in accordance with the following:

1. (CURRENTLY AMENDED) A method of supplying an underfill material for a semiconductor chip, comprising:

locating a wafer which receives a conductive bump on an upward front side of the wafer, said conductive -bump to be received on a printed circuit board; and

transferring an underfill material sheet, adhered to a surface of a thin film member, onto the upward front side of the wafer, said underfill material sheet being made of an insulating non-conductive material.

2. (CURRENTLY AMENDED) A ~~The~~ method of supplying ~~according to claim 1~~ an underfill material for a semiconductor chip, comprising:

locating a wafer which receives a conductive bump on an upward front side of the wafer;  
transferring an underfill material sheet, adhered to a surface of a thin film member, onto the upward front side of the wafer by urging the underfill material sheet onto the upward front side of the wafer after softening the underfill material sheet when transferring the underfill material sheet onto the wafer; and

peeling the thin film member from the underfill material sheet after hardening the underfill material sheet.

6. (PREVIOUSLY AMENDED) A method of making a semiconductor chip, comprising:

forming a conductive bump on an upward front side of a wafer;  
reversing the wafer; and

transferring a resin sheet, adhered to a surface of a thin film member, to a backside of the wafer, so as to form a resin lamination on the backside of the wafer.

8. (PREVIOUSLY AMENDED) A method of making a semiconductor chip, comprising:
  - reversing a wafer receiving a conductive bump on an upward front side;
  - irradiating an X-ray on the wafer;
  - determining a cutting position on the wafer based on the X-ray penetrating through the wafer; and
  - dicing the wafer from a backside of the wafer based on the cutting position.
9. (PREVIOUSLY AMENDED) The method of making according to claim 8, further comprising:
  - forming a nick along a contour of the semiconductor chip on the backside of the wafer; and
  - forming an evaporated resin lamination on the backside of the wafer.
10. (ORIGINAL) The method of making according to claim 9, further comprising cutting out an individual semiconductor chip along the nick with an incision narrower than the nick after formation of the evaporated resin lamination.
11. (ORIGINAL) A method of making a semiconductor chip, comprising:
  - locating a wafer receiving a conductive bump on an upward front side;
  - adhering an underfill material sheet onto the upward front side of the wafer;
  - reversing the wafer; and
  - dicing the wafer from a backside of the wafer.
12. (ORIGINAL) The method of making according to claim 11, further comprising:
  - irradiating an electromagnetic wave on the wafer; and
  - determining a cutting position on the wafer based on the electromagnetic wave penetrating through the wafer.
13. (ORIGINAL) The method of making according to claim 11, further comprising:
  - forming a nick along a contour of the semiconductor chip on the backside of the wafer; and
  - forming an evaporated resin lamination on the backside of the wafer.

14. (ORIGINAL) The method of making according to claim 13, further comprising cutting out an individual semiconductor chip along the nick with an incision narrower than the nick after formation of the evaporated resin lamination.

29. (ORIGINAL) The method according to claim 8, wherein a shadow of the conductive bump is utilized to determine the cutting position.

30. (ORIGINAL) The method according to claim 8, wherein a shadow of a metal mark on the wafer is utilized to determine the cutting position.

31. (NEW) The method of supplying according to claim 1, wherein said underfill material sheet is made of a mixture of a thermosetting adhesive and a thermoplastic resin.

32. (NEW) The method of supplying according to claim 1, wherein a height of said conductive bump is set equal to or larger than a thickness of the underfill material sheet.

33. (NEW) The method of supplying according to claim 2, wherein said conductive bump is to be received on a printed circuit board

34. (NEW) The method of supplying according to claim 2, wherein said underfill material sheet is made of a mixture of a thermosetting adhesive and a thermoplastic resin.

35. (NEW) The method of supplying according to claim 2, wherein a height of said conductive bump is set equal to or larger than a thickness of the underfill material sheet.